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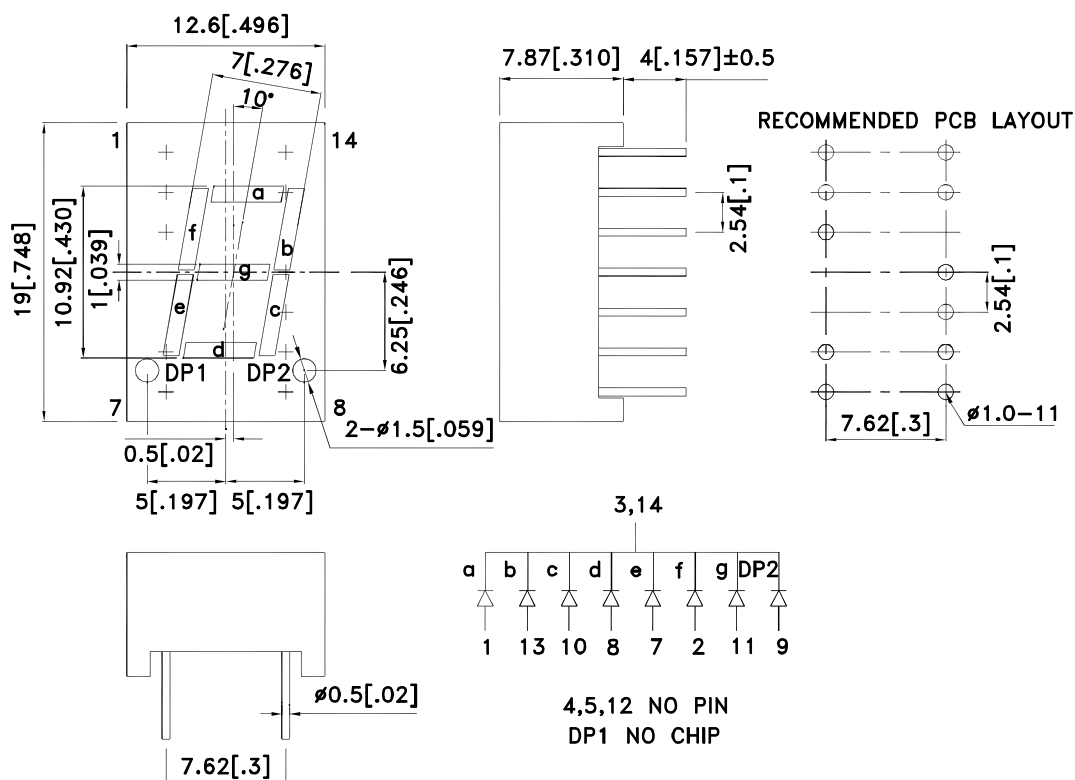Part Number: SC43-11EWA   High Efficiency Red

Features

● 0.43 inch digit height.

● Low current operation.

● Excellent character appearance.

● Easy mounting on P.C. boards or sockets.

● Mechanically rugged.

● Standard : gray face, white segment.

● RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram

RECOMMENDED PCB LAYOUT

3,14

a | b | c | d | e | f | g | DP2

1 | 13 | 10 | 8 | 7 | 2 | 11 | 9

4,5,12 NO PIN
DP1 NO CHIP

Notes:
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA Min.	Iv (ucd) [1] @ 10mA Typ.	Description
SC43-11EWA	High Efficiency Red (GaAsP/GaP)	White Diffused	5600	12000	Common Cathode, Rt. Hand Decimal.
			*1400	*3400	

Notes:
1. Luminous intensity/ luminous Flux: +/-15%.
   * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627	*627	nm	I_F=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625	*617	nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	I_F=20mA
C	Capacitance	High Efficiency Red	15		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage	High Efficiency Red	2.0	2.5	V	I_F=20mA
I_R	Reverse Current	High Efficiency Red		10	uA	V_R=5V

Notes:
1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
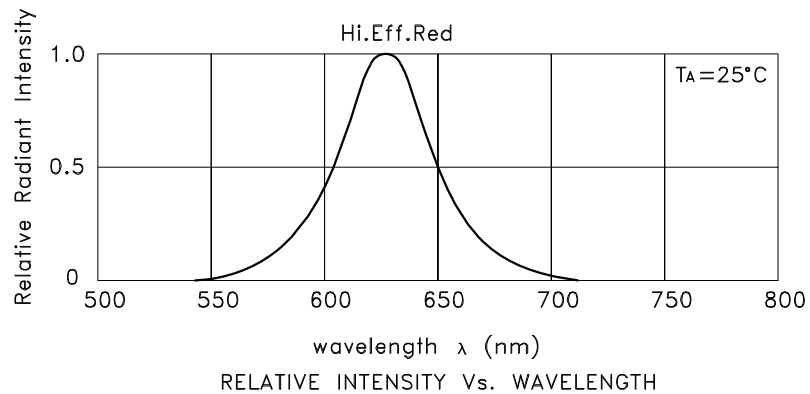* Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

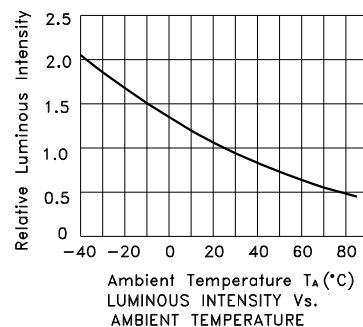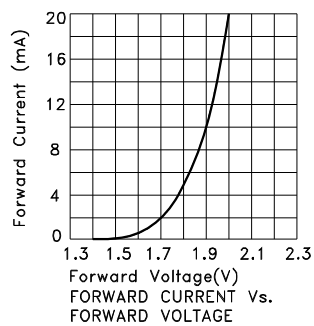| Parameter	High Efficiency Red	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	160	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	
Lead Solder Temperature[2]	260°C For 3-5 Seconds	

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.

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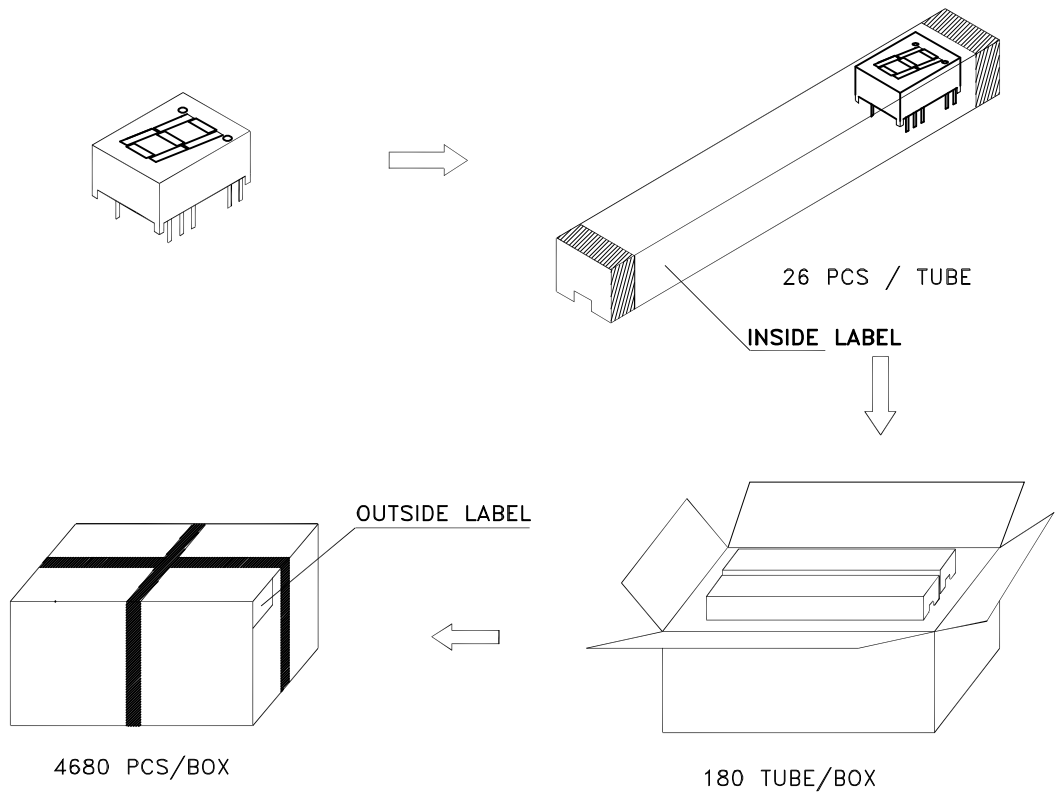**Hi.Eff.Red**

$T_A = 25°C$

Relative Radiant Intensity

wavelength λ (nm)

RELATIVE INTENSITY Vs. WAVELENGTH

High Efficiency Red   SC43-11EWA

Forward Current (mA)

Forward Voltage(V)

FORWARD CURRENT Vs.
FORWARD VOLTAGE

Luminous Intensity
Relative Value at IF=10mA

IF−Forward Current (mA)

LUMINOUS INTENSITY Vs.
FORWARD CURRENT

Forward Current (mA)

Ambient Temperature TA (°C)

FORWARD CURRENT
DERATING CURVE

Relative Luminous Intensity

Ambient Temperature TA (°C)

LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

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PACKING & LABEL SPECIFICATIONS   **SC43-11EWA**

26 PCS / TUBE

INSIDE LABEL

OUTSIDE LABEL

4680 PCS/BOX

180 TUBE/BOX

Inside Label On IC-tube

Kingbright
TYPE: SX43-11XXX
QTY: 26 PCS   CODE: xx

PASSED
XX XX XX
FQCX

Date

Number OF FQC

XXXXXXXXX-XXXX   RoHs Compliant

LOT NO.

Outside Label On Box

XXXXXX

SX43-11XXX

4680 PCS

Bin Code

XX

Number OF QA

QAx
xx xx xx
PASSED

Date

RoHS Compliant

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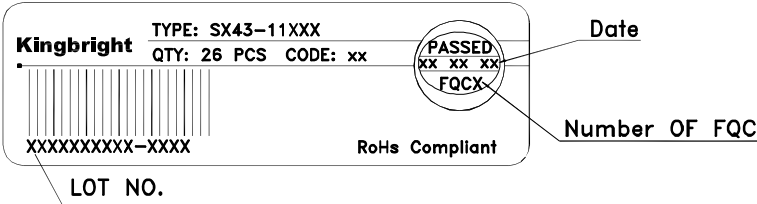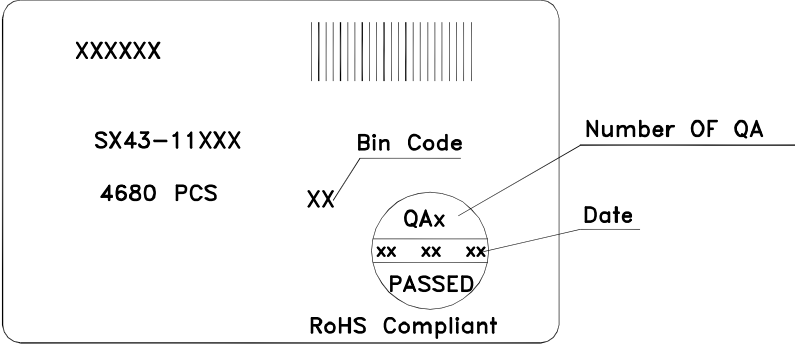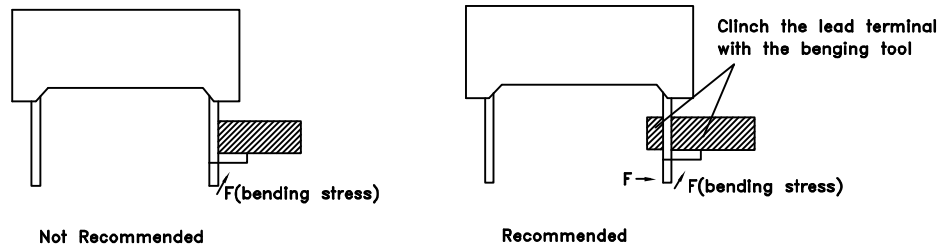
## THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming
Do not bend the component leads by hand without proper tools.
The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

Clinch the lead terminal with the benging tool

F(bending stress)

F → F(bending stress)

Not Recommended

Recommended

Installation
1. The installation process should not apply stress to the lead terminals.
2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.
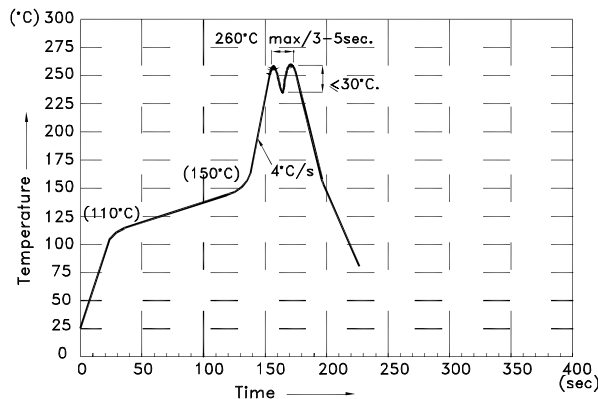
F

F

Not Recommended
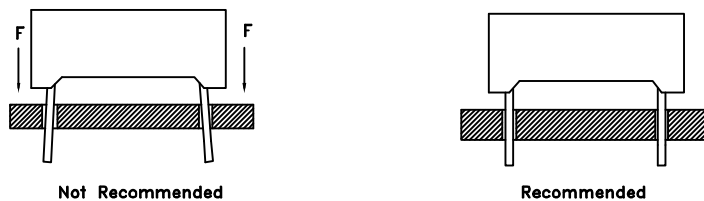
Recommended

3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.

>=5mm

>=5mm

Not Recommended

Recommended

Kingbright
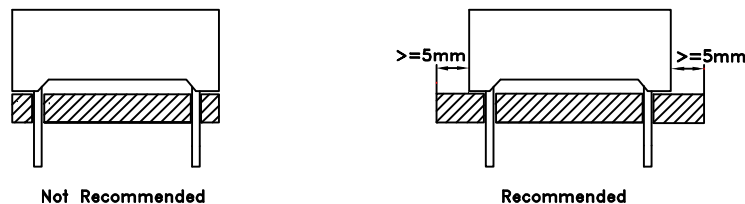
DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.

NOTES:
1. Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering , the PCB top-surface temperature should be kept below 105°C
5. No more than once.

Soldering General Notes:

1. Through-hole displays are incompatible with reflow soldering.

2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

1. Mild "no-clean" fluxes are recommended for use in soldering.

2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

1. Protective current-limiting resistors may be necessary to operate the Displays.

2. LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.

Recommended Set-up   invalid Set-up
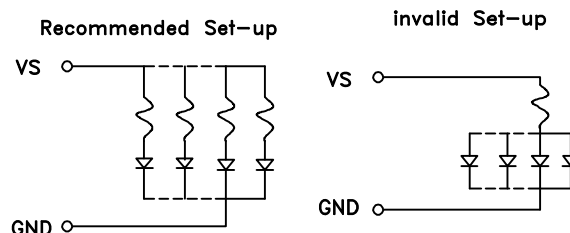
Detailed application notes are listed on our website.
http://www.kingbright.com/application_notes